

<b>ENGINEERING DEPT</b>	<b>PRODUCT SPECIFICATION</b>	<b>SPECNo: GS-BF-EN-042</b>
	<b>FOR PHONE JACK SERIES CONNECTOR</b>	<b>REV:3      Page 1 of 5</b>

### 1.0 SCOPE

This Product Specification covers the Phone Jack Series connector.

### 2.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

See sales drawings and other sections of this specification for the relevant reference documents. In cases where the specification differs from the drawings, the drawings take precedence.

### 3.0 DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

### 4.0 MATERIALS

See attached drawings

### 5.0 RATINGS

Rated current: 1.0A max

Rated voltage : 12V

Operating Temperature:-25 °C to +70°C

Storage Temperature: -5 °C to +80°C

**APPROVED BY:** Haiyong luo **CHECKED BY:** Max **VERIFIED:** Jackie

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	<b>FOR PHONE JACK SERIES CONNECTOR</b>	<b>REV:3 Page 2 of 5</b>

## 6. ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITIN	REQUIREMENT
6.1	Contact Resistance	Mate connectors with dry circuit(20mV,100mA Max) Spec: EIA-364-23B	Less than 30mΩ
6.2	Insulation Resistance	When applied DC 500V between adjacent terminal or ground Spec: EIA-364-21C	More than 100MΩ
6.3	Dielectric strength	When applied AC 500V 1 minute between adjacent terminal Spec: EIA-364-23B	No change

## 7.MECHANICAL REQUIREMENT

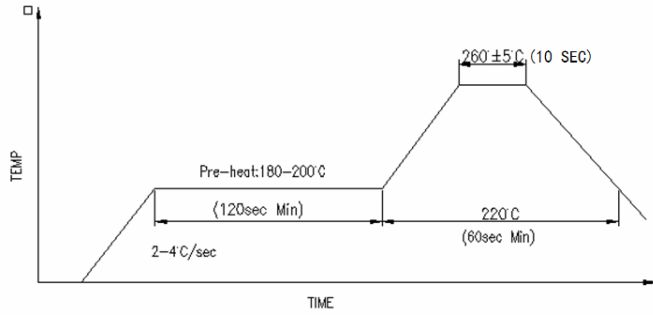
ITEM	DESCRIPTION	TEST CONDITIN	REQUIREMENT
7.1	Mating and Unmating force	Measures force necessary to mate connector assemblies at a rate of 25±3mm/Min Spec: EIA-364-13B	Insertion Force 30N Max Withdrawal Fore 3N Min
7.2	Durability	Operation Speed: 200 cycles/H. Durability Cycles: 5000 Cycle SPEC: EIA-364-9C	No damage, Cracks or part Dislocation Contact Resistance 50mΩ Max Insertion Force 30N Max Withdrawal Fore 3N Min
7.3	Terminal Retention Force	Axial pullout force on the terminal in the housing at a rate of 25±3mm/Min per minute Spec: EIA-364-13B	2.5N /PIN Min {250gf/pin. Min}

ENGINEERING DEPT	PRODUCT SPECIFICATION	SPECNo: GS-BF-EN-042
	FOR PHONE JACK SERIES CONNECTOR	REV:3 Page 3 of 5

## 8. ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITIN	REQUIREMENT
8.1	Solder ability	The surfaces to be tested shall be immersed in flux for a minimum of $5 \pm 0.5$ seconds. the temperature of the solder bath shall be maintained as measured below the surface on the solder at $245^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Spec: EIA 364-52	No evidence of physical damage, Wet solder coverage: 95%Min
8.2	Humidity Life	The connectors shall be mated and exposed to the condition of $40 \pm 2^{\circ}\text{C}$ with 90~95% Humidity for 96 hour; Recovery time 1~2 hours Spec: EIA-364-31B	No evidence of physical damage Contact Resistance 50mΩMax Insulation Resistance 100MΩMin
8.3	Salt Spray	Subject mated connectors to $35 \pm 2^{\circ}\text{C}$ and 5+/-1% salt condition for 48hours. After test, rinse the sample with water and recondition the room temperature for 2 hour Spec: EIA-364-26B	No detrimental corrosion allowed in contact area. contact resistance $\leq 50 \text{ m}\Omega$
8.4	Cold Resistance	Solder connectors on PCB ,expose to $-40 \pm 3^{\circ}\text{C}$ for 48 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2 hours, after which the specified measurements shall be performed.	No evidence of physical damage Contact Resistance 50mΩMax

ENGINEERING DEPT	PRODUCT SPECIFICATION	SPECNo: GS-BF-EN-042
	FOR PHONE JACK SERIES CONNECTOR	REV:3 Page 4 of 5

ITEM (条款)	DESCRIPTION (测试项目)	TEST CONDITIN (测试条件)	REQUIREMENT (必要条件)										
8.5	Thermal Shock	<p>Samples shall be placed in the test chamber with the test condition for 5 cycles</p> <table border="1"> <tr> <td>Temperature(°C)</td> <td>-55</td> <td>+25</td> <td>+85</td> <td>+25</td> </tr> <tr> <td>Time(minute)</td> <td>30</td> <td>5</td> <td>30</td> <td>5</td> </tr> </table> <p>Spec:EIA 364-32A</p>	Temperature(°C)	-55	+25	+85	+25	Time(minute)	30	5	30	5	<p>No evidence of physical damage</p> <p>Contact Resistance</p> <p>50mΩMax</p> <p>Insulation Resistance</p> <p>100MΩMin</p>
Temperature(°C)	-55	+25	+85	+25									
Time(minute)	30	5	30	5									
8.6	Temperature Life(Heat Aging)	<p>Mated Connector 85°C , 96 hours</p> <p>Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2 hours,</p> <p>Spec: EIA-364-17B.</p>	<p>No evidence of physical damage</p> <p>Contact resistance:</p> <p>Final:50 mΩ max.</p>										
8.7	Resistance to soldering heat	 <p>test condition for reflow soldering</p> <p>Spec: MIL-STD-202 F, Method 210 A</p>	<p>No evidence of physical damage</p>										

